

IRFP260MPbF

IR MOSFET™

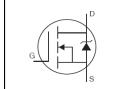
Features

- Advanced Process Technology
- Dynamic dv/dt Rating
- 175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Ease of Paralleling
- Simple Drive Requirements
- Lead-Free

Description

IR MOSFET[™] technology from Infineon utilizes advanced processing techniques to achieve extremely low on-resistance per silicon area. This benefit, combined with the fast switching speed and rugged device design that IR MOSFET[™] devices are well known for, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

The TO-247 package is preferred for commercialindustrial applications where higher power levels preclude the use of TO-220 devices. The TO-247 is similar but superior to the earlier TO-218 package because of its isolated mounting hole.



V _{(BR)DSS}	200V
R _{DS(on)} max.	0.04Ω
ID	50A



G	D	S
Gate	Drain	Source

Base part number	Packago Typo	Standard Pack		Orderable Part Number
Base part number	Package Type	Form	Quantity	Olderable Fait Nulliber
IRFP260MPbF	TO-247AD	Tube	25	IRFP260MPbF

Absolute Maximum Ratings

Symbol	Parameter	Max.	Units
I _D @ T _C = 25°C	Continuous Drain Current, V _{GS} @ 10V	50	
I _D @ T _C = 100°C	Continuous Drain Current, V _{GS} @ 10V	35	Α
I _{DM}	Pulsed Drain Current ①⑤	200	
P _D @T _C = 25°C	Maximum Power Dissipation	300	W
	Linear Derating Factor	2.0	W/°C
V _{GS}	Gate-to-Source Voltage	± 20	V
E _{AS}	Single Pulse Avalanche Energy 25	560	mJ
I _{AR}	Avalanche Current ①⑤	50	Α
E _{AR}	Repetitive Avalanche Energy ①	30	mJ
dv/dt	Peak Diode Recovery dv/dt3	10	V/ns
TJ	Operating Junction and	-55 to + 175	
T _{STG}	Storage Temperature Range	-55 10 + 175	°C
	Soldering Temperature, for 10 seconds (1.6mm from case)	300	
	Mounting torque, 6-32 or M3 screw	10 lbf•in (1.1N•m)	

Thermal Resistance

Symbol	Parameter	Тур.	Max.	Units
R _{θJC}	Junction-to-Case		0.50	
$R_{ hetaCS}$	Case-to-Sink, Flat, Greased Surface	0.24		°C/W
$R_{ heta JA}$	Junction-to-Ambient		40	



Electrical characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
V _{(BR)DSS}	Drain-to-Source Breakdown Voltage	200			V	V _{GS} = 0V, I _D = 250µA
$\Delta V_{(BR)DSS} / \Delta T_J$	Breakdown Voltage Temp. Coefficient		0.26	_	V/°C	Reference to 25° C, I _D = 1mA
R _{DS(on)}	Static Drain-to-Source On-Resistance			0.04	Ω	V _{GS} = 10V, I _D = 28A ④
V _{GS(th)}	Gate Threshold Voltage	2.0		4.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
gfs	Forward Trans conductance	27	_		S	V _{DS} = 50V, I _D = 28A④
1	Drain-to-Source Leakage Current			25		V _{DS} = 200V, V _{GS} = 0V
IDSS				250	μΑ	V _{DS} = 160V,V _{GS} = 0V,T _J =150°C
	Gate-to-Source Forward Leakage			100	nA	V _{GS} = 20V
	Gate-to-Source Reverse Leakage			-100	IIA	V _{GS} = -20V

Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

1	Parameter	Min	Tvp.	Max	Units	Conditions
Diode Cl	haracteristics			_	-	
C _{rss}	Reverse Transfer Capacitance		161			f = 1.0MHz, See Fig.5
C _{oss}	Output Capacitance		603		pF	V _{DS} = 25V
C _{iss}	Input Capacitance		4057			V _{GS} = 0V
Ls	Internal Source Inductance		13		1111	from package
L _D	Internal Drain Inductance		5.0		nH	Between lead, 6mm (0.25in.)
t _f	Fall Time		48			V _{GS} = 10V, See Fig.10④
t _{d(off)}	Turn-Off Delay Time		55		115	R _G = 1.8Ω
t _r	Rise Time		60		ns	I _D = 28A
t _{d(on)}	Turn-On Delay Time		17			V _{DD} = 100V
Q_{gd}	Gate-to-Drain Charge			110		V_{GS} = 10V, See Fig.6 and 13 \oplus
Q_{gs}	Gate-to-Source Charge			38	nC	V _{DS} = 160V
Qg	Total Gate Charge			234		I _D = 28A

	Parameter	Min.	Тур.	Max.	Units	Conditions
I _S	Continuous Source Current (Body Diode)			50		MOSFET symbol showing the
I _{SM}	Pulsed Source Current (Body Diode) ①			200		integral reverse p-n junction diode.
V_{SD}	Diode Forward Voltage			1.3	V	$T_{J} = 25^{\circ}C, I_{S} = 28A, V_{GS} = 0V ④$
t _{rr}	Reverse Recovery Time		268	402	ns	T _J = 25°C ,I _F = 28A
Q _{rr}	Reverse Recovery Charge		1.9	2.8	μC	di/dt = 100A/µs ④

Notes:

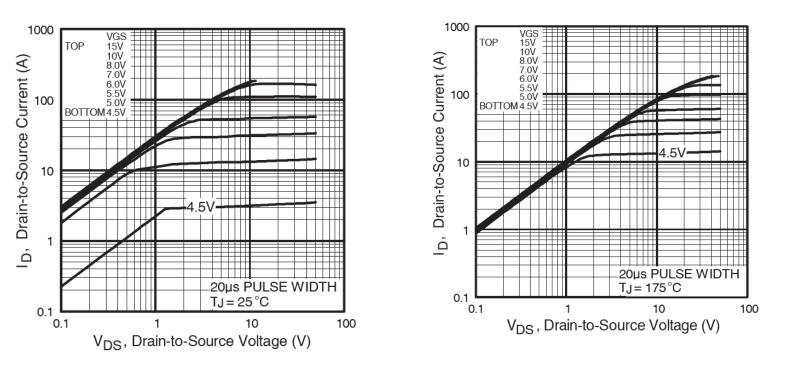
① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11).

 $\ensuremath{{}^{\circ}}$ Starting T_J = 25°C, L = 1.5mH, R_G = 25 Ω , I_{AS} = 28A.(See fig. 12).

 $\label{eq:ISD} \ensuremath{\mathbb{S}} I_{SD} \leq 28A, \ di/dt \leq 486A/\mu s, \ V_{DD} \leq V_{(BR)DSS}, \ T_J \leq 175^\circ C.$

④ Pulse width \leq 400µs; duty cycle \leq 2%.





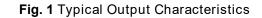


Fig. 2 Typical Output Characteristics

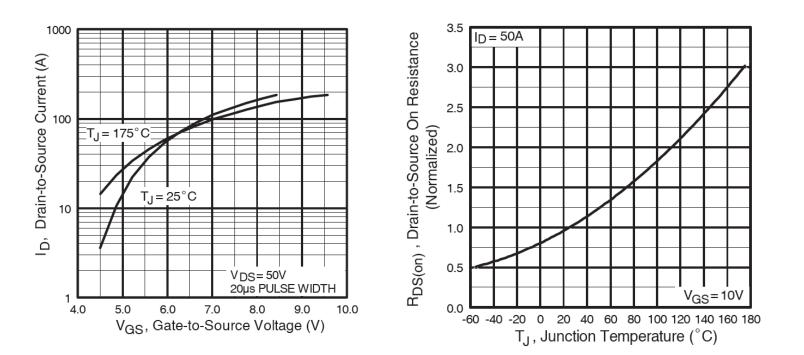
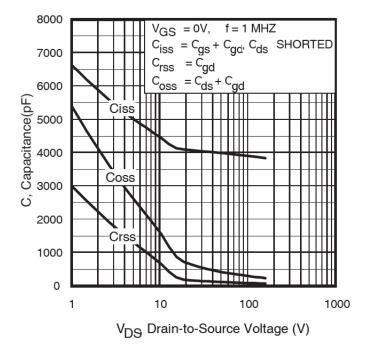
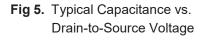


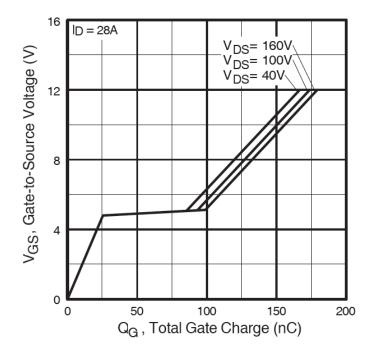
Fig. 3 Typical Transfer Characteristics



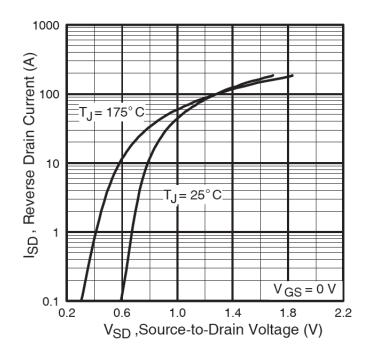














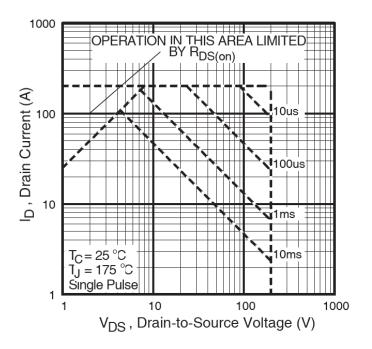
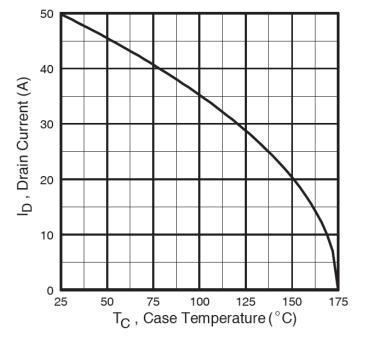
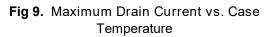


Fig 8. Maximum Safe Operating Area







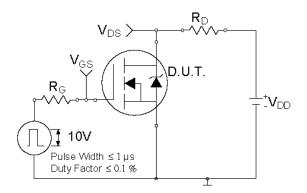


Fig 10a. Switching Time Test Circuit

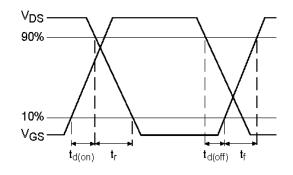
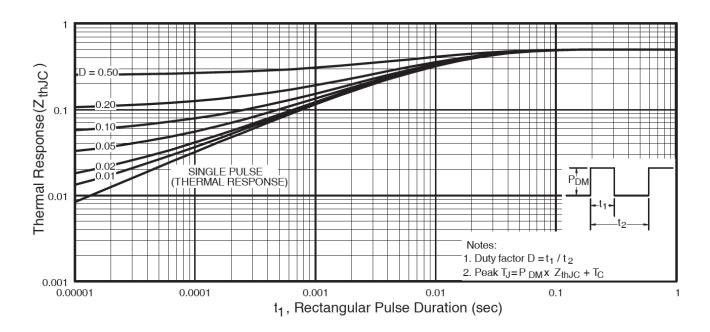
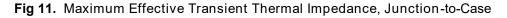


Fig 10a. Switching Time Waveforms





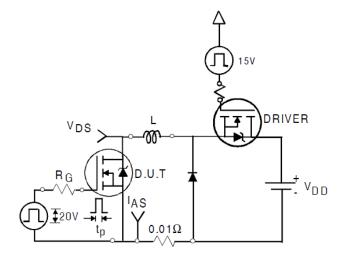


Fig. 12a. Unclamped Inductive Test Circuit

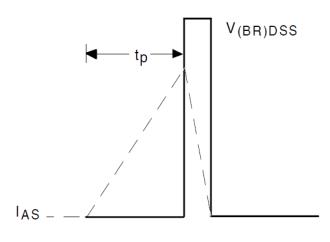


Fig. 12b. Unclamped Inductive Waveforms

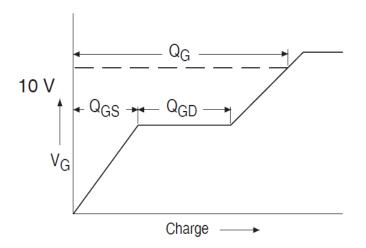


Fig 13a. Basic Gate Charge Waveform

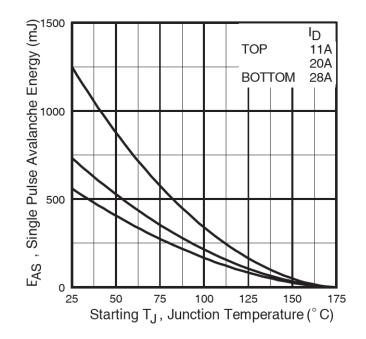


Fig 12c. Maximum Avalanche Energy vs. Drain Current

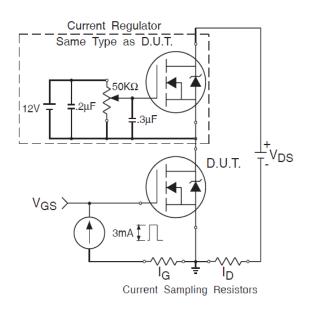
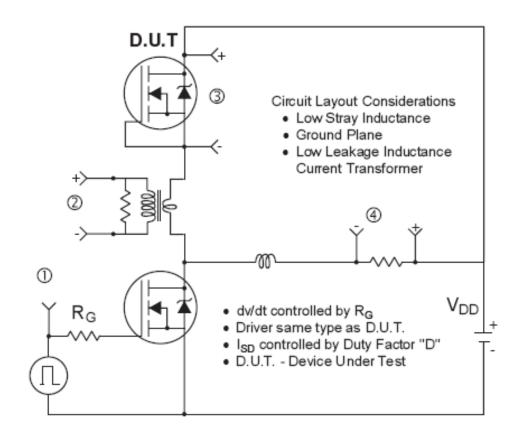
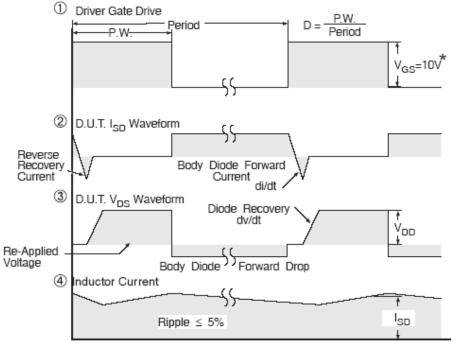
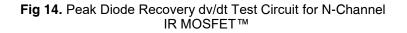


Fig 13b. Gate Charge Test Circuit



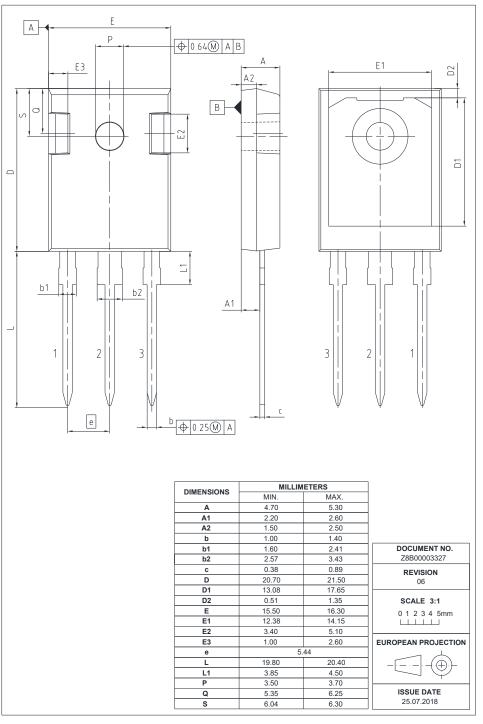


* V_{GS} = 5V for Logic Level Devices

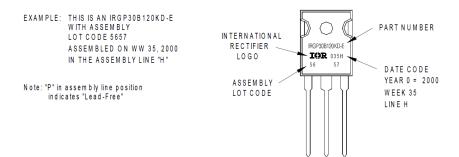




TO-247AD Package Outline (Dimensions are shown in millimeters (inches))



TO-247AD Part Marking Information





Revision History

Date	Comments				
	Updated datasheet with corporate template				
05/28/2020	Updated Package picture-page1				
03/26/2020	 Corrected from "Hexfet power MOSFET" to "IR MOSFET™" -page1 &7 				
	Corrected part marking from TO-247AC to TO-247AD on page 8.				

Published by Infineon Technologies AG 81726 München, Germany © Infineon Technologies AG 2015 All Rights Reserved.

IMPORTANT NOTICE

The information given in this document shall in <u>no event</u> be regarded as a guarantee of conditions or characteristics ("Beschaffenheitsgarantie"). With respect to any examples, hints or any typical values stated herein and/or any information regarding the application of the product, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.

In addition, any information given in this document is subject to customer's compliance with its obligations stated in this document and any applicable legal requirements, norms and standards concerning customer's products and any use of the product of Infineon Technologies in customer's applications.

The data contained in this document is exclusively intended for technically trained staff. It is the responsibility of customer's technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to such application.

For further information on the product, technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies office (<u>www.infineon.com</u>).

WARNINGS

Due to technical requirements products may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies office.

Except as otherwise explicitly approved by Infineon Technologies in a written document signed by authorized representatives of Infineon Technologies, Infineon Technologies' products may <u>not</u> be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal injury.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Infineon: IRFP260MPBF